

Features

- Surface Mount Package Ideally Suited for Automated Insertion
- Very Low Leakage Current
- **Lead Free/RoHS Compliant (Note 3)**

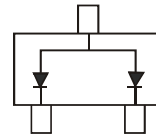
Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.008 grams (approximate)

SOT-23



TOP VIEW



TOP VIEW
Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	85	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	60	V
Forward Continuous Current (Note 2)	Single diode	160	mA
	Double diode	140	
Repetitive Peak Forward Current (Note 2)	I _{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs	4.0	A
	@ t = 1.0ms	1.0	
	@ t = 1.0s	0.5	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P _D	250	mW
Thermal Resistance Junction to Ambient Air (Note 2)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V _{(BR)R}	85	—	—	V	I _R = 100µA
Forward Voltage	V _F	—	—	0.90	V	I _F = 1.0mA
				1.0		I _F = 10mA
				1.1		I _F = 50mA
				1.25		I _F = 150mA
Leakage Current (Note 1)	I _R	—	—	5.0	nA	V _R = 75V
				80		V _R = 75V, T _J = 150°C
Total Capacitance	C _T	—	3	—	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	3.0	µs	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

- Notes:
1. Short duration pulse test used to minimize self-heating effect.
 2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. No purposefully added lead.

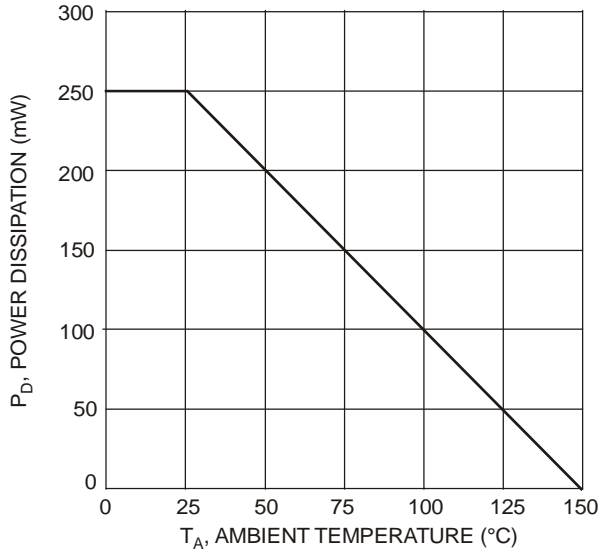


Fig. 1 Power Derating Curve, Total Package

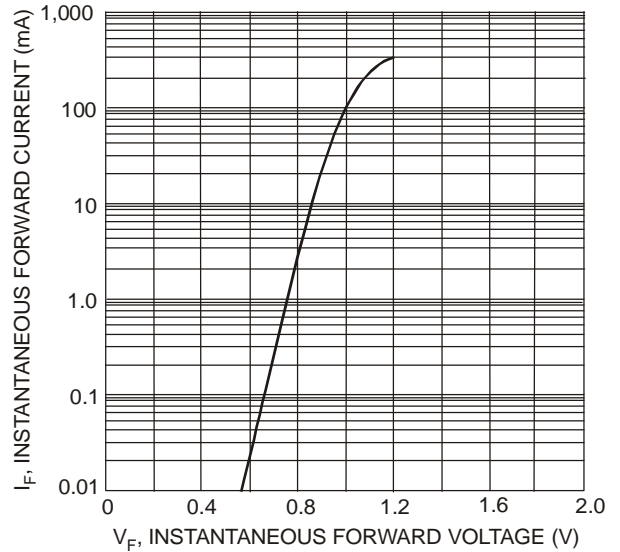


Fig. 2 Typical Forward Characteristics, Per Element

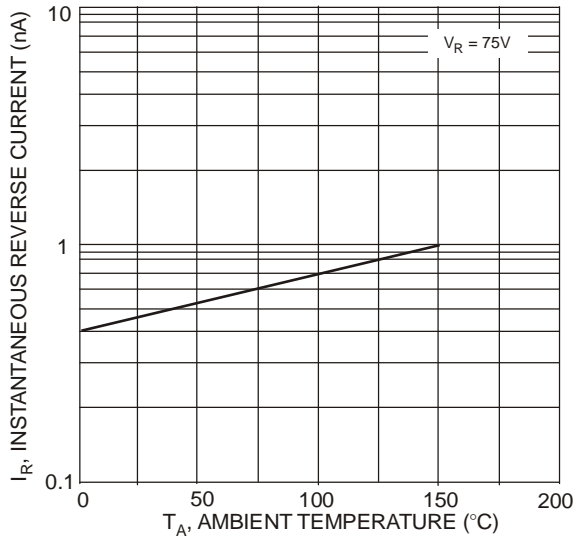


Fig. 3 Typical Reverse Characteristics, Per Element

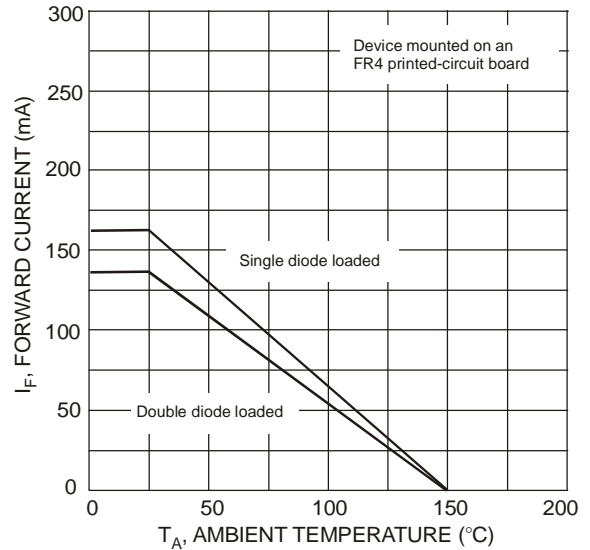


Fig. 4 Current Derating Curve, Per Element

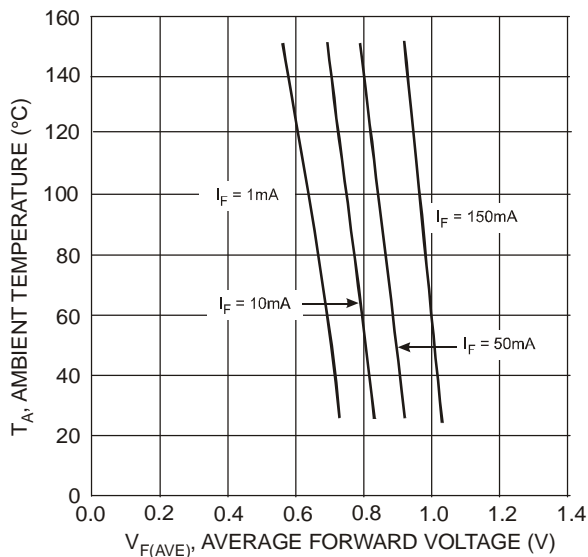


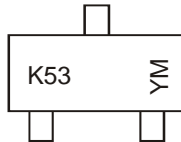
Fig. 5 Typical Forward Voltage vs. Ambient Temperature, Per Element

Ordering Information (Note 4)

Part Number	Case	Packaging
BAW156-7-F	SOT-23	3000/Tape & Reel

Notes: 4. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



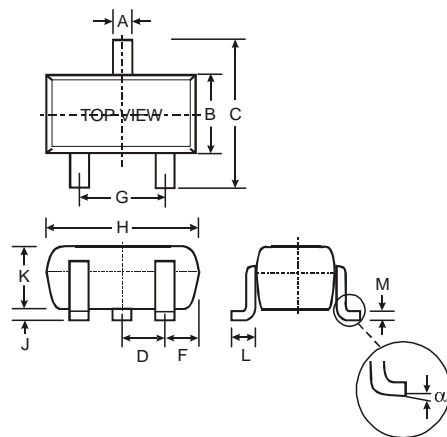
K53 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: N = 2002
 M = Month ex: 9 = September

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	J	K	L	M	N	P	R	S	T	U	V	W	X	Y	Z

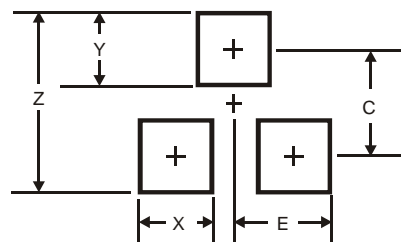
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-23		
Dim	Min	Max
A	0.37	0.51
B	1.20	1.40
C	2.30	2.50
D	0.89	1.03
F	0.45	0.60
G	1.78	2.05
H	2.80	3.00
J	0.013	0.10
K	0.903	1.10
L	0.45	0.61
M	0.085	0.180
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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